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## 300mA LDO Linear Regulators with Internal Microprocessor Reset Circuit

#### **General Description**

The MAX6469-MAX6484 are low-dropout linear regulators with a fully integrated microprocessor reset circuit. Each is available with preset output voltages from +1.5V to +3.3V in 100mV increments and delivers up to 300mA of load current. These devices consume only 82µA of supply current. The low supply current, low dropout voltage, and integrated reset functionality make these devices ideal for battery-powered portable equipment.

The MAX6469-MAX6484 include a reset output that indicates when the regulator output drops below standard microprocessor supply tolerances (-7.5% or -12.5% of nominal output voltage). This eliminates the need for an external microprocessor supervisor, while ensuring that supply voltages and clock oscillators have stabilized before processor activity is enabled. Push-pull and opendrain active-low reset outputs are available, with reset timeout periods of 2.5ms, 20ms, 150ms, or 1200ms (min).

The MAX6469/MAX6470/MAX6473-MAX6478/MAX6481-MAX6484 also have a shutdown feature that reduces the supply current to 1.0µA (max). The MAX6471-MAX6474/ MAX6479-MAX6482 offer a manual reset input to assert a microprocessor reset while the regulator output is within specification. The MAX6475/MAX6476/MAX6483/ MAX6484 feature a remote feedback sense pin for use with an external NPN transistor for higher-current applications. The MAX6469-MAX6476 are available in 6-pin SOT23 and 8-pin thin QFN packages. The MAX6477-MAX6484 are available in a 3 × 3 chip-scale package (UCSP™). All devices are specified for operation from -40°C to +85°C.

#### **Applications**

Hand-Held Instruments (PDAs, Palmtops) PCMCIA Cards/USB Devices Cellular/Cordless Telephones CD/DVD Drives Notebook Computers Digital Cameras Bluetooth Modules/Wireless LAN

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Pin Configurations appear at end of data sheet. Typical Operating Circuits appear at end of data sheet.

#### Features

- ♦ 3 × 3 UCSP, 6-Pin SOT23, and 8-Pin QFN Packages
- ♦ Preset +1.5V to +3.3V Output (100mV Increments)
- ♦ SET Pin for Adjustable Output Voltage
- ♦ 178µVRMS LDO Output Voltage Noise (MAX6477-MAX6484)
- ♦ ±2.3% Accuracy Over Temperature
- ♦ Guaranteed 300mA Output Current
- **♦ Low Dropout Voltage** 55mV at 150mA 114mV at 300mA
- ♦ 82µA Supply Current, 1µA Shutdown Current
- ♦ Input Reverse Current, Thermal and Short-Circuit **Protection**
- ♦ Microprocessor Reset with Four Timeout Options
- **♦ Push-Pull or Open-Drain RESET**
- ♦ Manual Reset Input
- ♦ Remote Feedback Sense

#### **Ordering Information**

PART	TEMP RANGE	PIN- PACKAGE
MAX6469UTDT	-40°C to +85°C	6 SOT23-6
MAX6469TAD_*	-40°C to +85°C	8 Thin QFN
MAX6470UTDT	-40°C to +85°C	6 SOT23-6
MAX6470TAD_*	-40°C to +85°C	8 Thin QFN

<sup>\*</sup>Future product—contact factory for availability.

**Note:** The first "\_\_"are placeholders for the output voltage levels of the devices. Desired output voltages are set by the suffix found in the Output Voltage Suffix Guide (see Table 1). The third " " is a placeholder for the reset threshold accuracy. Desired reset threshold accuracy is set by the suffix found in the Reset Threshold Accuracy Guide (see Table 2). The "\_" following the D is a placeholder for the reset timeout delay time. Desired reset timeout delay time is set by the suffix found in the Reset Timeout Delay Guide (see Table 3). For example, the MAX6481BL30BD4-T has a 3.0V output voltage, 12.5% reset threshold tolerance, and a 1200ms (min) reset timeout delay. Sample stock is generally available on standard versions only (see the Standard Versions table, Table 4). Standard versions require a minimum order increment of 2.5k units. Nonstandard versions must be ordered in 10k-unit increments. Contact factory for availability.

Ordering Information continued at end of data sheet.

MIXIM

#### **ABSOLUTE MAXIMUM RATINGS**

(All voltages referenced to GND, un	nless otherwise noted.)
IN, SHDN, OUT, FB	
MR, SET	0.3V to (V <sub>IN</sub> + 0.3V)
RESET (push-pull)	0.3V to (Vout + 0.3V)
RESET (open drain)	0.3V to +7V
OUT Short Circuit	Continuous
Input/Output Current (all pins exce	pt IN and OUT) 20mA

Continuous Power Dissipation (T <sub>A</sub> = +70°C)	
3 x 3 UCSP (derate 10.5mW/°C above +70°C)	840mW
6-Pin SOT23 (derate 9.1mW/°C above +70°C)	727mW
8-Lead Thin QFN (derate 24.4mW/°C above +70	0°C).1951mW
Operating Temperature Range	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range65	
Lead Temperature (soldering, 10s)	
Bump Reflow Temperature (Note 1)	+235°C

**Note 1:** This device is constructed using a unique set of packaging techniques that impose a limit on the thermal profile the device can be exposed to during board level solder attach and rework. This limit permits only the use of the solder profiles recommended in the industry-standard specification, JEDEC 020A, paragraph 7.6, Table 3 for IR/VPR and Convection reflow. Preheating is required. Hand or wave soldering is not allowed.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

 $(V_{IN} = V_{OUT} + 0.5V \text{ or } +2.5V, \text{ whichever is greater, } C_{OUT} = 3.3\mu\text{F}, T_{A} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}.$  Typical specifications are at  $T_{A} = +25^{\circ}\text{C}, \text{ unless otherwise noted.})$  (Note 2)

PARAMETER	SYMBOL	CONDITIO	MIN	TYP	MAX	UNITS	
Input Voltage Range	VIN		2.5		5.5	V	
Input Undervoltage Lockout	V <sub>U</sub> VLO	V <sub>IN</sub> falling		2.25		2.47	V
Cupply Current (Cround Current)	lo.	I <sub>OUT</sub> = 0			82	136	
Supply Current (Ground Current)	IQ	I <sub>OUT</sub> = 300mA			96		μΑ
Shutdown Supply Current	ISHDN	T <sub>A</sub> = +25°C			0.1	1	μΑ
REGULATOR CIRCUIT							
Output Current				300			mA
Output Voltage Accuracy (Fixed		$I_{OUT} = 150 \text{mA}, T_{A} = +25^{\circ}$	Õ	-1.3		+1.3	
Output Voltage Operation, See		$I_{OUT} = 150 \text{mA}, T_{A} = -40 ^{\circ} \text{C}$	C to +85°C	-2.3		+2.3	%
Table 1)		1mA ≤ I <sub>OUT</sub> ≤ 300mA, T <sub>A</sub>	$1mA \le I_{OUT} \le 300mA$ , $T_{A} = -40^{\circ}C$ to $+85^{\circ}C$			+2.7	
Adjustable Output Voltage Range				VSET		5.0	V
SET Reference Voltage	V <sub>SET</sub>			1.200	1.229	1.258	V
SET Dual Mode <sup>™</sup> Threshold					185		mV
SET Input Leakage Current	ISET	V <sub>SET</sub> = 0, +1.2V (Note 3)		±20	±100	nA	
			I <sub>OUT</sub> = 50mA		23	32	
		V <sub>OUT</sub> = +3.3V (fixed output operation)	I <sub>OUT</sub> = 150mA		55	90	_
			$I_{OUT} = 300mA$		114	180	
		Vout = +3.0V	$I_{OUT} = 50mA$		25	40	
			$I_{OUT} = 150mA$		61	100	
Dropout Voltage	41/5.0	(fixed output operation)	$I_{OUT} = 300mA$		114	190	mV
(Notes 3, 4)	$\Delta V_{DO}$	. 0.01/	$I_{OUT} = 50mA$		26	50	IIIV
		V <sub>OUT</sub> = +2.8V (fixed output operation)	$I_{OUT} = 150mA$		65	110	
		(lixed output operation)	$I_{OUT} = 300 mA$		137	210	
		\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	$I_{OUT} = 50mA$	·	30	60	
		V <sub>OUT</sub> = +2.5V (fixed output operation)	$I_{OUT} = 150mA$		75	150	
		(IIACG Output Operation)	$I_{OUT} = 300mA$		158	250	

Dual Mode is a trademark of Maxim Integrated Products, Inc.

#### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{IN} = V_{OUT} + 0.5V \text{ or } +2.5V, \text{ whichever is greater, } C_{OUT} = 3.3\mu\text{F}, T_{A} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}.$  Typical specifications are at  $T_{A} = +25^{\circ}\text{C}, \text{ unless otherwise noted.})$  (Note 2)

PARAMETER	SYMBOL	CONDI	MIN	TYP	MAX	UNITS	
Output Current Limit		V <sub>IN</sub> ≥ 2.5V (Note 3)	450			mA	
Input Reverse Leakage Current (OUT to IN Leakage Current)		V <sub>IN</sub> = 4V, V <sub>OUT</sub> = 5.5V		0.01	1.5	μА	
Startup Time Response		Rising edge of V <sub>IN</sub> or 3 within specification, Ri I <sub>OUT</sub> = 10mA			20		μs
SHDN Input Low Voltage	VIL					$0.3 \times V_{IN}$	V
SHDN Input High Voltage	VIH			$0.7 \times V_{IN}$			V
SHDN Input Current		SHDN = V <sub>IN</sub> or GND		-1	0.1	+1	μΑ
Thermal-Shutdown Temperature	T <sub>SHDN</sub>				180		degrees
Thermal-Shutdown Hysteresis	$\Delta T_{SHDN}$				20		degrees
Line Regulation		$V_{OUT} = 1.5V, 2.5V \le V$ $I_{OUT} = 10mA$	I <sub>IN</sub> ≤ 5.5V,		0.09		%/V
Load Regulation		V <sub>OUT</sub> = 1.5V, V <sub>IN</sub> = 2.5 150mA	5V, 1mA≤I <sub>OUT</sub> ≤		0.2		%
Outrout Valle are Naise		8Hz to 1MHz, C <sub>IN</sub> =	MAX6467-MAX6476		355		
Output Voltage Noise		$0.1\mu F$ , $I_{OUT} = 100 \text{mA}$	MAX6477-MAX6484		178		μV <sub>RMS</sub>
RESET CIRCUIT							
Vout Reset Threshold		MAX64 A		90	92.5	95	
(V <sub>FB</sub> for MAX6475/MAX6476/ MAX6483/MAX6484) (Note 5)	VTHOUT	MAX64B	MAX64B		87.5	90	%Vout
V <sub>OUT</sub> to Reset Delay (V <sub>FB</sub> for MAX6475/MAX6476/ MAX6483/MAX6484)					35		μs
		D1		2.5	3.75	5.0	
Reset Timeout Period	+	D2		20	30	40	ma
(Note 6)	t <sub>RP</sub>	D3		150	225	300	ms
		D4		1200	1800	2400	
MR Input Low Voltage	VIL					0.3 × Vout	V
MR Input High Voltage	VIH	(Note 3)		0.7 × Vout			V
MR Minimum Input Pulse				1			μs
MR Glitch Rejection					120		ns
MR to Reset Delay					200		ns
MR Pullup Resistance		MR to OUT		25	40	70	kΩ
RESET Output Voltage	\/a:		50μA, RESET asserted			0.3	V
(Open Drain)	V <sub>OL</sub>	V <sub>OUT</sub> ≥ 1.5V, I <sub>SINK</sub> = 3				0.4	V



#### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{IN} = V_{OUT} + 0.5V \text{ or } +2.5V, \text{ whichever is greater, } C_{OUT} = 3.3\mu\text{F}, T_{A} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}.$  Typical specifications are at  $T_{A} = +25^{\circ}\text{C}, \text{ unless otherwise noted.}$ ) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Open-Drain Reset Output Leakage Current	I <sub>LKG</sub>	(Note 3)			1	μΑ
RESET Output Voltage Push-Pull		V <sub>OUT</sub> ≥ 1.0V, I <sub>SINK</sub> = 50µA, RESET asserted			0.3	
	V <sub>OL</sub>	V <sub>OUT</sub> ≥ 1.0V, I <sub>SINK</sub> = 50µA, RESET asserted			0.4	V
	V <sub>OH</sub>	V <sub>OUT</sub> ≥ 1.0V, I <sub>SINK</sub> = 50µA, RESET asserted	0.8 × Vout			

Note 2: All devices are 100% production tested at +25°C and are guaranteed by correlation for T<sub>A</sub> = T<sub>MIN</sub> to T<sub>MAX</sub>.

Note 3: Guaranteed by design.

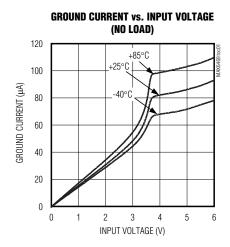
Note 4: Dropout voltage is defined as (VIN - VOUT) when VOUT is 2% below the value of VOUT for VIN = VOUT(NOM) + 1V.

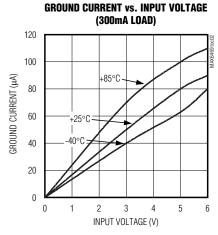
Note 5: MAX6473/MAX6474/MAX6481/MAX6482 are guaranteed by design for V<sub>OUT</sub> < 2.5V.

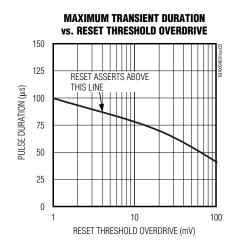
Note 6: Select the reset timeout period using the Reset Timeout Delay Guide (Table 3). Insert the appropriate suffix in the part number when ordering.

#### Typical Operating Characteristics

 $(V_{IN} = 5V, V_{OUT} = 3.3V, C_{OUT} = 3.3\mu F, T_A = +25^{\circ}C, unless otherwise noted.)$ 

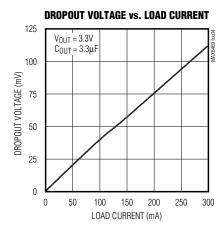


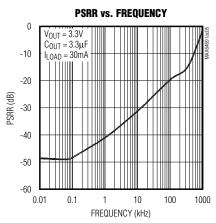


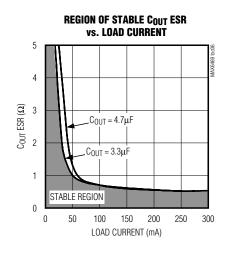


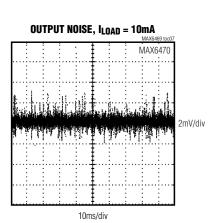
#### Typical Operating Characteristics (continued)

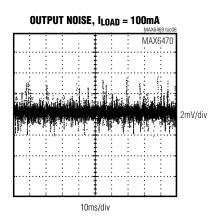
 $(V_{IN} = 5V, V_{OUT} = 3.3V, C_{OUT} = 3.3\mu F, T_A = +25^{\circ}C$ , unless otherwise noted.)

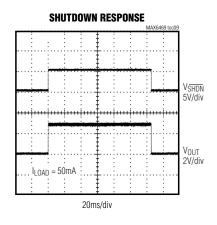


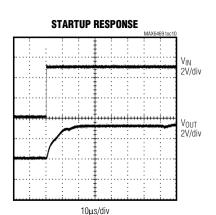


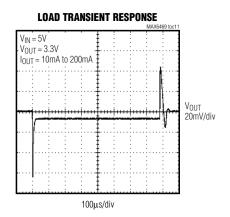


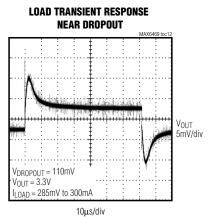






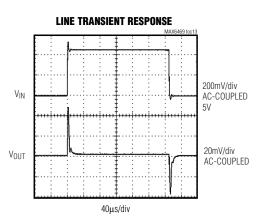


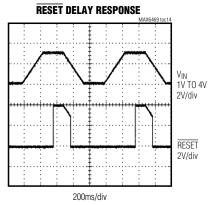


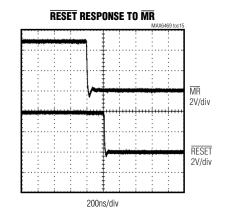


#### Typical Operating Characteristics (continued)

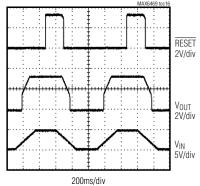
( $V_{IN}$  = 5V,  $V_{OUT}$  = 3.3V,  $C_{OUT}$  = 3.3 $\mu$ F,  $T_A$  = +25 $^{\circ}$ C, unless otherwise noted.)



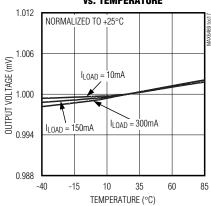




#### $\overline{\text{RESET}}$ response to $v_{\text{IN}}$ rising



## CHANGE IN OUTPUT VOLTAGE vs. TEMPERATURE



#### MAX6469/MAX6470/MAX6477/MAX6478 Pin Description

Р	IN	вимр		FUNCTION
MAX6469	/MAX6470	MAX6477/MAX6478	NAME	FUNCTION
SOT23	QFN	UCSP		
1	1, 2	A1	IN	Regulator Input. Bypass IN to GND with a 0.1µF capacitor.
2	3	A2	GND	Ground. This pin also functions as a heatsink. Solder to large pads or the circuit board ground plane to maximize thermal dissipation.
3	4	А3	SHDN	Active-Low Shutdown Input. Connect SHDN to V <sub>IN</sub> for normal operation.
4	5	C3	RESET	Active-Low Reset Output. RESET remains low while Vout is below the reset threshold. RESET remains low for the duration of the reset timeout period after the reset conditions are terminated. RESET is available in open-drain and push-pull configurations.
5	6	C2	SET	Feedback Input for Externally Setting the Output Voltage. Connect SET to GND to select the preset output voltage. Connect SET to an external resistor-divider network for adjustable output operation.
6	7, 8	C1	OUT	Regulator Output. Bypass OUT to GND with a minimum 3.3µF low-ESR capacitor.

#### MAX6471/MAX6472/MAX6479/MAX6480 Pin Description

	IN /MAX6472	BUMP MAX6479/MAX6480	NAME	FUNCTION
SOT23	QFN	UCSP		
1	1, 2	A1	IN	Regulator Input. Bypass IN to GND with a 0.1µF capacitor.
2	3	A2	GND	Ground. This pin also functions as a heatsink. Solder to large pads or the circuit board ground plane to maximize thermal dissipation.
3	4	АЗ	MR	Active-Low Manual Reset Input. The reset output is asserted while $\overline{\text{MR}}$ is pulled low and remains asserted for the duration of the reset timeout period after $\overline{\text{MR}}$ transitions from low to high. Leave $\overline{\text{MR}}$ unconnected or connect to V <sub>OUT</sub> if not used. $\overline{\text{MR}}$ has an internal pullup resistor of 40k $\Omega$ (typ) to V <sub>OUT</sub> .
4	5	C3	RESET	Active-Low Reset Output. RESET remains low while Vout is below the reset threshold or while MR is held low. RESET remains low for the duration of the reset timeout period after the reset conditions are terminated. RESET is available in open-drain and push-pull configurations.
5	6	C2	SET	Feedback Input for Externally Setting the Output Voltage. Connect SET to GND to select the preset output voltage. Connect SET to an external resistor-divider network for adjustable output operation.
6	7, 8	C1	OUT	Regulator Output. Bypass OUT to GND with a minimum 3.3µF low-ESR capacitor.

#### MAX6473/MAX6474/MAX6481/MAX6482 Pin Description

		X6473/MAX6474 MAX6481/MAX6482 NAM		FUNCTION
<b>SOT23</b>	1, 2	A1	IN	Regulator Input. Bypass IN to GND with a 0.1µF capacitor.
2	3	A2	GND	Ground. This pin also functions as a heatsink. Solder to large pads or the circuit board ground plane to maximize thermal dissipation.
3	4	АЗ	SHDN	Active-Low Shutdown Input. Connect SHDN to V <sub>IN</sub> for normal operation.
4	5	C3	RESET	Active-Low Reset Output. RESET remains low while VOUT is below the reset threshold or while MR is held low. RESET remains low for the duration of the reset timeout period after the reset conditions are terminated. RESET is available in open-drain and push-pull configurations.
5	6	C2	MR	Active-Low Manual Reset Input. The reset output is asserted while $\overline{\text{MR}}$ is pulled low and remains asserted for the duration of the reset timeout period after $\overline{\text{MR}}$ transitions from low to high. Leave $\overline{\text{MR}}$ unconnected or connect to V <sub>OUT</sub> if not used. $\overline{\text{MR}}$ has an internal pullup resistor of 40k $\Omega$ (typ) to V <sub>OUT</sub> .
6	7, 8	C1	OUT	Regulator Output. Bypass OUT to GND with a minimum 3.3µF (min) low-ESR capacitor.

#### MAX6475/MAX6476/MAX6483/MAX6484 Pin Description

	IN	вимр	NAME	FUNCTION
MAX6475	/MAX6476	MAX6483/MAX6484		
SOT23	QFN	UCSP		
1	1, 2	A1	IN	Regulator Input. Bypass IN to GND with a 0.1µF capacitor.
2	3	A2	GND	Ground. This pin also functions as a heatsink. Solder to large pads or the circuit board ground plane to maximize thermal dissipation.
3	4	А3	SHDN	Active-Low Shutdown Input. Connect SHDN to V <sub>IN</sub> for normal operation.
4	5	C3	RESET	Active-Low Reset Output. RESET remains low while FB is below the reset threshold. RESET remains low for the duration of the reset timeout period after the reset conditions are terminated. RESET is available in open-drain and push-pull configurations.
5	6	C2	FB	Feedback Input for Linear Regulator Controller or Remote Sense Applications. Connect FB to the external load (V <sub>CC</sub> ) to obtain the fixed output voltage.
6	7, 8	C1	OUT	Regulator Output. Bypass OUT to GND with a minimum 3.3µF low-ESR capacitor.

#### **Detailed Description**

The MAX6469–MAX6484 are ultra-low, quiescent current, low-dropout linear regulators with an integrated microprocessor reset circuit. These devices guarantee 300mA (min) drive capabilities and are available with preset output voltages in 100mV increments between +1.5V and +3.3V. The internal reset circuit monitors the regulator output voltage and asserts the reset output when the regulator output is below the microprocessor supply tolerance.

#### Regulator

The regulator core operates with +2.5V to +5.5V input voltage range. The output voltage is offered in 100mV increments between +1.5V and +3.3V (contact factory for other output voltage options). The MAX6469–MAX6472/MAX6477–MAX6480 offer an adjustable output voltage implemented with an external resistor-divider network between OUT, SET, and GND (Figure 1). SET must be connected to either GND for fixed VOUT or to an external divider for adjustable VOUT. The MAX6469–MAX6472/MAX6477–MAX6480 automatically determine the feedback path depending on the connection of SET. The *Typical Operating Circuit* shows a typical connection for the MAX6469. OUT is an internally regulated low-dropout (LDO) linear regulator that powers a microprocessor.

#### **Reset Circuit**

The reset supervisor circuit is fully integrated in the MAX6469–MAX6484 and uses the same reference voltage as the regulator. Two supply tolerance reset thresholds, -7.5% and -12.5%, are provided for each type of device.

- **-7.5% Reset:** Reset does not assert until the regulator output voltage is at least -5% out of tolerance and always asserts before the regulator output voltage is -10% out of tolerance.
- **-12.5% Reset:** Reset does not assert until the regulator output voltage is at least -10% out of tolerance and always asserts before the regulator output voltage is -15% out of tolerance.

#### **RESET Output**

A  $\mu P$ 's reset input starts the  $\mu P$  in a known state. The MAX6469-MAX6484  $\mu P$  supervisory circuits assert RESET during power-up, power-down, and brownout conditions. RESET asserts when the input voltage is below the undervoltage lockout threshold. RESET asserts when VOUT is below the reset threshold and remains asserted for at least the minimum selected reset timeout period (trp, see Table 3) after VIN rises above the undervoltage lockout threshold and VOUT rises

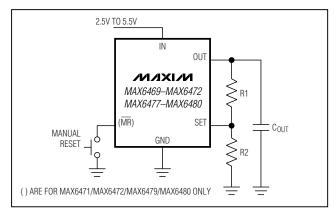


Figure 1. Adjustable Output Voltage Configuration

above the reset threshold.  $\overline{\text{RESET}}$  asserts when  $\overline{\text{MR}}$  is pulled low (MAX6471–MAX6474/MAX6479–MAX6482).  $\overline{\text{RESET}}$  asserts when  $\overline{\text{SHDN}}$  is pulled low (MAX6469/MAX6470/MAX6473–MAX6478/MAX6481–MAX6484).

#### Shutdown (MAX6469/MAX6470/MAX6473-MAX6479/MAX6480-MAX6484 only)

SHDN allows the regulator to shut down, thereby reducing the total I<sub>IN</sub> consumption of the device. SHDN provides a digitally controlled active-low shutdown. In shutdown mode, the pass transistor, control circuit, and reference turn off to reduce the supply current to below 1µA. Connect SHDN to IN for normal operation.

## Manual Reset Input (MAX6471–MAX6474/MAX6479–MAX6482 only)

Many µP-based products require manual reset capability, allowing the operator, a test technician, or external logic circuitry to initiate a reset. A logic low on MR asserts reset while the regulator output voltage is still within tolerance.

Reset remains asserted while  $\overline{\text{MR}}$  is low and for the reset timeout period (tRP) after  $\overline{\text{MR}}$  returns high. The  $\overline{\text{MR}}$  input has an internal pullup of  $40\text{k}\Omega$  (typ) to OUT.  $\overline{\text{MR}}$  can be driven with TTL/CMOS logic levels or with open-drain/collector outputs. Connect a normally open switch from  $\overline{\text{MR}}$  to GND to create a manual reset function; external debounce circuitry is not required. If  $\overline{\text{MR}}$  is driven from long cables or the device is used in a noisy environment, connect a  $0.1\mu\text{F}$  capacitor from  $\overline{\text{MR}}$  to GND to provide additional noise immunity.

## Feedback Input (MAX6475/MAX6476/MAX6483/MAX6484 only)

The feedback input (FB) connects to an internal resistor-divider network (*Functional Diagram*). FB is not internally connected to V<sub>OUT</sub>, and as a result can be used to

remotely sense the output voltage of the device. Using FB with an external NPN transistor, the current drive capability can be increased according to the following equation (see Figure 2):

$$I_{OUT(TOTAL)} = I_{OUT} \times (\beta+1)$$

The external NPN pass transistor must meet specifications for current gain, power dissipation, and collector current. The beta influences the maximum output current the circuit can deliver. The largest guaranteed output current is given by  $I_{LOAD}$  (max) = 300mA × beta (min). The transistor's rated power dissipation must exceed the actual power dissipated in the transistor. The power dissipated (PD) equals the maximum load current ( $I_{LOAD}$  (max)) times the maximum input-to-output voltage differential: PD =  $I_{LOAD}$  (max) × ( $V_{IN}$  (max) -  $V_{OUT}$ ). The rated transistor collector current must exceed the maximum load current.

#### **Reverse Leakage Protection**

An internal circuit monitors the input and output voltages. When the output voltage is greater than the input voltage, the internal pass transistor and parasitic diodes turn off. OUT powers the device. There is no leakage path from OUT to IN. Therefore, the output can be powered from an auxiliary supply such as a backup battery without additional blocking diodes (Figure 3). SHDN should be left floating when the battery is removed for proper operation. Current into OUT is typically 0.01µA when VIN is removed.

#### **Current Limit**

The MAX6469-MAX6484 include an internal current-limit circuit that monitors and controls the pass transistor's gate voltage, limiting the output current to 450mA

(min). The output can be shorted to ground for an indefinite period without damaging the part.

#### **Thermal Shutdown**

When the junction temperature (TJ) exceeds +180°C (typ), the thermal sensor signals the shutdown logic, turning off the pass transistor and allowing the IC to cool. The thermal sensor turns the pass transistor on again after the IC's junction temperature cools by 20°C, resulting in a pulsed output during continuous thermal overload conditions. Thermal overload protection is designed to protect the MAX6469–MAX6484 in the event of fault conditions. For continuous operation, do not exceed the absolute maximum junction temperature rating of TJMAX = +150°C.

#### **Operating Region and Power Dissipation**

The MAX6469–MAX6484's maximum power dissipation depends on the thermal resistance of the case and circuit board, the temperature difference between the die junction and the ambient air, and the rate of airflow. The power dissipation across the device is:

The maximum power dissipation is:

$$P_{MAX} = (T_J - T_A) / (\emptyset_{JB} + \emptyset_{BA})$$

where T<sub>J</sub> - T<sub>A</sub> is the temperature difference between the die junction and the surrounding air,  $\varnothing_{JB}$  (or  $\varnothing_{JC}$ ) is the thermal resistance of the package, and  $\varnothing_{BA}$  is the thermal resistance through the PC board, copper traces, and other materials to the surrounding air. The MAX6469–MAX6476 QFN package  $\varnothing_{JC}$  = 41°C/W, and the MAX6469–MAX6476 SOT package  $\varnothing_{JC}$  = 110°C/W.

The MAX6469–MAX6484's ground pin (GND) performs the dual function of providing an electrical connection

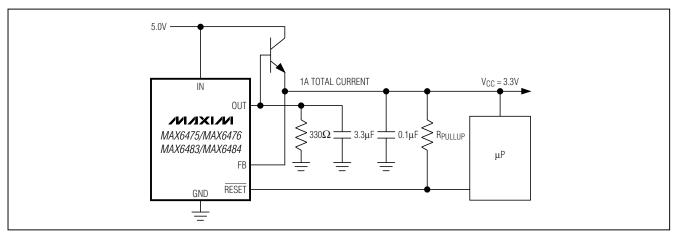


Figure 2. High-Current, External Transistor Application

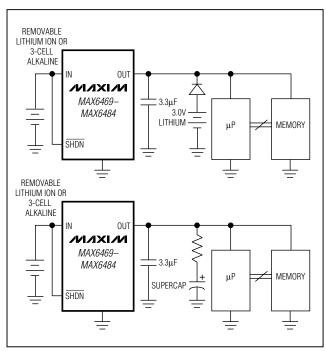


Figure 3. Battery Backup

to the system ground and channeling heat away. Connect GND to the system ground using a large pad or ground plane. For continuous operation, do not exceed the absolute maximum junction temperature rating of T<sub>JMAX</sub> = +150°C.

## \_Applications Information

#### **Output Voltage Selection**

The MAX6469–MAX6484 feature dual-mode operation: they operate in either a preset output voltage mode or an adjustable mode. In preset voltage mode, internal feedback resistors set the MAX6469–MAX6484's output from +1.5V to +3.3V (see Table 1). Select this mode by connecting SET to ground (MAX6469–MAX6472/MAX6477–MAX6480). In adjustable mode, select an output between 1.25V and 5.5V using two external resistors connected as a voltage-divider to SET (Figure 1). The output voltage is set by the following equation:

$$VOUT = VSET (1 + R1 / R2)$$

where  $V_{SET} = 1.23V$ . To simplify resistor selection:

$$R_1 = R_2 (V_{OUT} / V_{SFT} - 1)$$

Choose R2 =  $50k\Omega$  to maintain stability, accuracy and high-frequency power-supply rejection. Avoid selecting resistor values greater than  $100k\Omega$ . In preset voltage mode, the impedance between SET and ground should always be less than  $50k\Omega$ . In most applications, connect SET directly to ground.

#### Capacitor Selection and Regulator Stability

For stable operation over the full temperature range and with load currents up to 300mA, use a 3.3 $\mu$ F (min) ceramic output capacitor with an ESR < 0.2 $\Omega$ . To reduce noise and improve load transient response, stability, and power-supply rejection, use large output capacitor values such as 10 $\mu$ F.

Note that some ceramic capacitors exhibit large capacitance and ESR variation with temperature. With capacitor dielectrics such as Z5U and Y5V, use 4.7µF or more to ensure stability over temperature. With X7R or X5R capacitor dielectrics, 3.3µF should be sufficient at all operating temperatures. Higher ESR capacitors require more capacitance to maintain stability. A graph of the Region of Stable ESR vs. Load Current is shown in the *Typical Operating Characteristics*.

To improve power-supply rejection and transient response, use a 1µF capacitor between IN and GND.

The MAX6469-MAX6484 remain stable with purely resistive loads or current loads up to 300mA.

#### **Reset Transient Immunity**

The reset circuit is relatively immune to short-duration, falling Vout transients. The *Typical Operating Characteristics* section shows a graph of the Maximum Transient Duration vs. Reset Threshold Overdrive for which reset is not asserted. The graph was produced using falling Vout transients starting at Vout and ending below the reset threshold by the magnitude indicated (reset threshold overdrive). The graph shows the maximum pulse width that a falling Vout transient can typically have without triggering a reset pulse. As the amplitude of the transient increases (i.e., goes further below the reset threshold), the maximum allowable pulse width decreases. Typically, a Vout transient that goes only 10mV below the reset threshold and lasts for 75µs does not trigger a reset pulse.

#### **Power Dissipation Consideration**

For the SOT23 package, any pin except the SET pin can be used as a heatsink. If the SET pin is used as a heatsink, excessive parasitic capacitance can affect stability. For the QFN package, a metal on the back side of a package connects to GND of the chip. This metal can be used as a heatsink.

#### **UCSP Package Consideration**

For general UCSP package information and PC layout considerations, refer to Maxim Application Note: *Wafer-Level Chip-Board-Scale Package*.

#### **UCSP Reliability**

The chip-scale package (UCSP) represents a unique packaging form factor that might not perform equally to

a packaged product through traditional mechanical reliability tests. CSP reliability is integrally linked to the user's assembly methods, circuit board material, and usage environment. The user should closely review these areas when considering a CSP package. Performance through operating life test and moisture resistance remains uncompromised, because it is primarily determined by the wafer-fabrication process.

Mechanical stress performance is a greater consideration for a CSP package. CSPs are attached through direct solder contact to the user's PC board, forgoing the inherent stress relief of a packaged product lead frame. Solder-joint contact integrity must be considered. Information on Maxim's qualification plan, test data, and recommendations are detailed in the UCSP application note on Maxim's website at www.maxim-ic.com.

Table 1. Output Voltage Suffix Guide

SUFFIX	OUTPUT VOLTAGE (V)
15	1.5
16	1.6
17	1.7
18	1.8
19	1.9
20	2.0
21	2.1
22	2.2
23	2.3
24	2.4
25	2.5
26	2.6
27	2.7
28	2.8
285	2.85
29	2.9
30	3.0
31	3.1
32	3.2
33	3.3

**Note:** Factory-trimmed custom output voltages may be available; contact factory for availability.

**Table 2. Reset Threshold Accuracy Guide** 

SUFFIX	V <sub>OUT</sub> RESET TOLERANCE (%)
А	-7.5
В	-12.5

**Table 3. Reset Timeout Delay Guide** 

SUFFIX	MINIMUM RESET TIMEOUT PERIOD (ms)				
D1	2.5				
D2	20				
D3	150				
D4	1200				

**Table 4. Standard Versions** 

DEVICE	TOP MARK					
MAX6469TA15BD3	ADO					
MAX6469TA18AD3	ADP					
MAX6469TA25BD3	ADQ					
MAX6469TA28AD3	ACT					
MAX6469TA30BD3	ADR					
MAX6469TA33AD3	ADS					
MAX6469UT15BD3	ABKS					
MAX6469UT18AD3	ABKT					
MAX6469UT25BD3	ABKU					
MAX6469UT28AD3	ABFF					
MAX6469UT285AD3 ABMZ						
MAX6469UT285BD3 ABNA						
MAX6469UT30BD3 ABKV						
MAX6469UT33AD3	ABKW					
MAX6470TA15BD3	ADT					
MAX6470TA18AD3	ADU					
MAX6470TA25BD3	ADV					
MAX6470TA28AD3	ADW					
MAX6470UT285AD3	ABNB					
MAX6470UT285BD3	ABNC					
MAX6470TA30BD3	ADY					
MAX6470TA33AD3	ACU					
MAX6470UT15BD3	ABKX					
MAX6470UT18AD3	ABKY					
MAX6470UT25BD3	ABKZ					
MAX6470UT28AD3	ABLA					
MAX6470UT30BD3	ABLB					
MAX6470UT33AD3	ABLC					
<b>MAX6471</b> TA15AD3	ADZ					
MAX6471TA18BD3	AEA					
MAX6471TA25AD3	AEB					
MAX6471TA28BD3	AEC					
MAX6471TA30AD3	AED					
MAX6471TA33BD3	AEE					
MAX6471UT15AD3	ABLD					
MAX6471UT18BD3	ABLE					
MAX6471UT25AD3	ABLF					

MAX6471UT28BD3  MAX6471UT30AD3  MAX6471UT33BD3  MAX6472TA15AD3  MAX6472TA18BD3  MAX6472TA25AD3  MAX6472TA28BD3  MAX6472TA30AD3  MAX6472TA33BD3  MAX6472TA33BD3  MAX6472UT15AD3	ABLG ABLH ABLI AEF ACW AEG AEH AEI				
MAX6471UT33BD3  MAX6472TA15AD3  MAX6472TA18BD3  MAX6472TA25AD3  MAX6472TA28BD3  MAX6472TA30AD3  MAX6472TA33BD3	ABLI AEF ACW AEG AEH				
MAX6472TA15AD3  MAX6472TA18BD3  MAX6472TA25AD3  MAX6472TA28BD3  MAX6472TA30AD3  MAX6472TA33BD3	AEF ACW AEG AEH				
MAX6472TA18BD3  MAX6472TA25AD3  MAX6472TA28BD3  MAX6472TA30AD3  MAX6472TA33BD3	ACW AEG AEH				
MAX6472TA25AD3  MAX6472TA28BD3  MAX6472TA30AD3  MAX6472TA33BD3	AEG AEH				
MAX6472TA28BD3 MAX6472TA30AD3 MAX6472TA33BD3	AEH				
MAX6472TA30AD3 MAX6472TA33BD3					
MAX6472TA33BD3	AEI				
MAX6472UT15AD3	AEJ				
	ABLJ				
MAX6472UT18BD3	ABFI				
MAX6472UT25AD3	ABLK				
MAX6472UT28BD3	ABLL				
MAX6472UT30AD3	ABLM				
MAX6472UT33BD3	ABLN				
MAX6473TA15AD3	AEK				
MAX6473TA18BD3	AEL				
MAX6473TA25AD3	AEM				
MAX6473TA28BD3	AEN				
MAX6473TA30AD3	AEO				
MAX6473TA33BD3	AEP				
MAX6473UT15AD3	ABLO				
MAX6473UT18BD3	ABLP				
MAX6473UT25AD3	ABLQ				
MAX6473UT28BD3	ABLR				
MAX6473UT30AD3	ABLS				
MAX6473UT33BD3	ABLT				
MAX6474TA15AD3	AEQ				
MAX6474TA18BD3	AER				
MAX6474TA25AD3	/ \LI I				

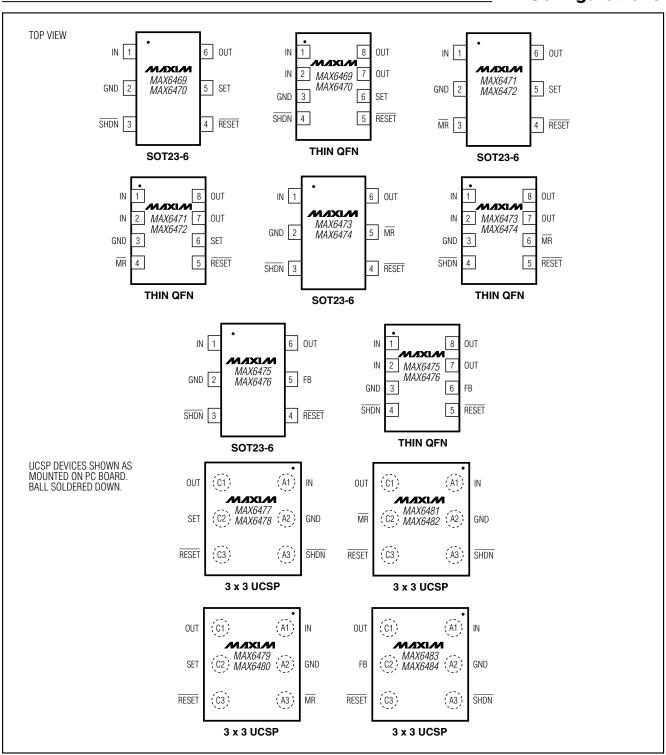
**Table 4. Standard Versions (continued)** 

DEVICE	TOP MARK				
MAX6474TA28BD3	AET				
MAX6474TA30AD3	AEU				
MAX6474TA33BD3	AEV				
MAX6474UT15AD3	ABLU				
MAX6474UT18BD3	ABLV				
MAX6474UT25AD3	ABLW				
MAX6474UT28BD3	ABLX				
MAX6474UT30AD3	ABLY				
MAX6474UT33BD3	ABLZ				
MAX6475TA15BD3	AEW				
MAX6475TA18AD3	AEX				
MAX6475TA25BD3	AEY				
MAX6475TA28AD3	AEZ				
MAX6475TA30BD3	AFA				
MAX6475TA33AD3	ACZ				
MAX6475UT15BD3	ABMA				
MAX6475UT18AD3	ABMB				
MAX6475UT25BD3	ABMC				
MAX6475UT28AD3	ABMD				
MAX6475UT30BD3	ABME				
MAX6475UT33AD3	ABFL				
MAX6476TA15BD3	AFB				
MAX6476TA18AD3	AFC				
MAX6476TA25BD3	AFD				
MAX6476TA28AD3	AFE				
MAX6476TA30BD3	AEF				
MAX6476TA33AD3	AFG				
MAX6476UT15BD3	ABMF				
MAX6476UT18AD3	ABMG				
MAX6476UT25BD3	ABMH				
MAX6476UT28AD3	ABMI				
MAX6476UT30BD3	ABMJ				
MAX6476UT33AD3	ABMK				
MAX6477BL15BD3	ABW				
MAX6477BL18AD3	ABG				
MAX6477BL25BD3	ABX				
MAX6477BL28AD3	ABY				
MAX6477BL30BD3	ABZ				
MAX6477BL33AD3	ACA				
MAX6478BL15BD3	ACB				
MAX6478BL18AD3	ACC				
MAX6478BL25BD3	ACD				

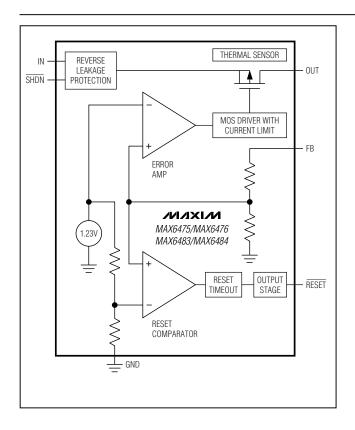
DEVICE	TOP MARK				
MAX6478BL28AD3	ACE				
MAX6478BL30BD3	ACF				
MAX6478BL33AD3	ACG				
MAX6479BL15AD3	ACH				
MAX6479BL18BD3	ACI				
MAX6479BL25AD3	ACJ				
MAX6479BL28BD3	ACK				
MAX6479BL30AD3	ACL				
MAX6479BL33BD3	ACM				
MAX6480BL15BD3	ACN				
MAX6480BL18AD3	ACO				
MAX6480BL25BD3	ACP				
MAX6480BL28AD3	ACQ				
MAX6480BL30BD3	ACR				
MAX6480BL33AD3	ABJ				
MAX6481BL15BD3	ACS				
MAX6481BL18AD3	ACT				
MAX6481BL25BD3	ACU				
MAX6481BL28AD3	ACV				
MAX6481BL30BD3	ACW				
MAX6481BL33AD3	ACX				
MAX6482BL15BD3	ACY				
MAX6482BL18AD3	ACZ				
MAX6482BL25BD3	ADA				
MAX6482BL28AD3	ADB				
MAX6482BL30BD3	ADC				
MAX6482BL33AD3	ADD				
MAX6483BL15BD3	ADE				
MAX6483BL18AD3	ADF				
MAX6483BL25BD3	ADG				
MAX6483BL28AD3	ADH				
MAX6483BL30BD3	ADI				
MAX6483BL33AD3	ADJ				
MAX6484BL15BD3	ADK				
MAX6484BL18AD3	ADL				
MAX6484BL25BD3	ADM				
MAX6484BL28AD3	ADN				
MAX6484BL30BD3	ADO				
MAX6484BL33AD3 ADP					

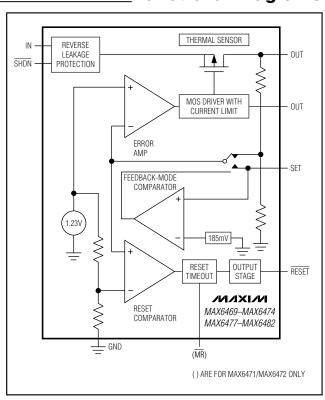
Sample stock is generally available on standard versions only. Standard versions require a minimum order increment of 2.5k units. Nonstandard versions must be ordered in 10k-unit increments. Contact factory for availability.

#### Pin Configurations



## Functional Diagrams





#### **Typical Operating Circuit**

# 2.5V TO 5.5V IN SHDN OUT MAX6469/MAX6470 MAX6477/MAX6478 SET GND RESET GND GND GND

#### \_Chip Information

TRANSISTOR COUNT: 1041 PROCESS: BICMOS

#### Ordering Information (continued)

PART		TEMP RANGE	PIN- PACKAGE
MAX6471UT_	DT	-40°C to +85°C	6 SOT23-6
MAX6471TA	_D_*	-40°C to +85°C	8 Thin QFN
MAX6472UT_	DT	-40°C to +85°C	6 SOT23-6
MAX6472TA	_D_*	-40°C to +85°C	8 Thin QFN
MAX6473UT_	DT	-40°C to +85°C	6 SOT23-6
MAX6473TA	_D_*	-40°C to +85°C	8 Thin QFN
MAX6474UT_	DT	-40°C to +85°C	6 SOT23-6
MAX6474TA	_D_*	-40°C to +85°C	8 Thin QFN
MAX6475UT_	DT*	-40°C to +85°C	6 SOT23-6
MAX6475TA	_D_*	-40°C to +85°C	8 Thin QFN
MAX6476UT_	DT	-40°C to +85°C	6 SOT23-6
MAX6476TA	_D_*	-40°C to +85°C	8 Thin QFN
MAX6477BL	DT*	-40°C to +85°C	6 UCSP
MAX6478BL	DT*	-40°C to +85°C	6 UCSP
MAX6479BL_	DT*	-40°C to +85°C	6 UCSP
MAX6480BL	DT*	-40°C to +85°C	6 UCSP
MAX6481BL_	DT*	-40°C to +85°C	6 UCSP
MAX6482BL	DT*	-40°C to +85°C	6 UCSP
MAX6483BL_	DT*	-40°C to +85°C	6 UCSP
MAX6484BL_	DT*	-40°C to +85°C	6 UCSP

<sup>\*</sup>Future product—contact factory for availability.

Note: The first "\_\_"are placeholders for the output voltage levels of the devices. Desired output voltages are set by the suffix found in the Output Voltage Suffix Guide (see Table 1). The third "\_" is a placeholder for the reset threshold accuracy. Desired reset threshold accuracy is set by the suffix found in the Reset Threshold Accuracy Guide (see Table 2). The "\_" following the D is a placeholder for the reset timeout delay time. Desired reset timeout delay time is set by the suffix found in the Reset Timeout Delay Guide (see Table 3). For example, the MAX6481BL30BD4-T has a 3.0V output voltage, 12.5% reset threshold tolerance, and a 1200ms (min) reset timeout delay. Sample stock is generally available on standard versions only (see the Standard Versions table, Table 4). Standard versions require a minimum order increment of 2.5k units. Nonstandard versions must be ordered in 10k-unit increments. Contact factory for availability.

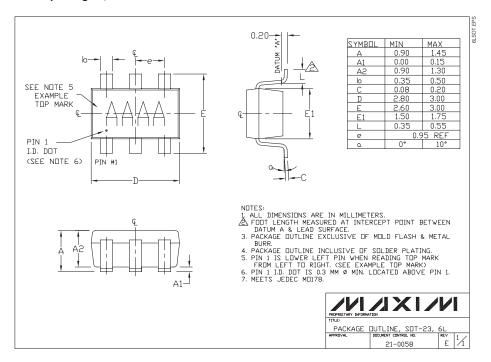
#### **Selector Guide**

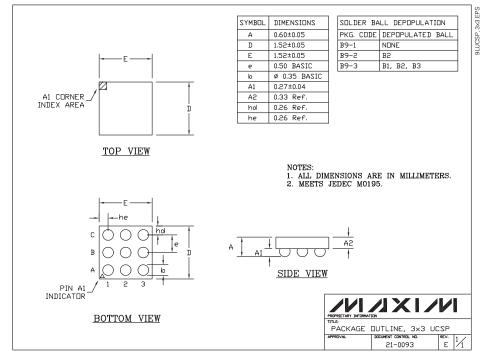
	_		1				
PART	SET	SHDN	MR	FB	PUSH-PULL RESET	OPEN-DRAIN RESET	PACKAGE
MAX6469	√	√	_	_	√	_	SOT23-6/8-QFN
MAX6470	√	√	_	_	_	√	SOT23-6/8-QFN
MAX6471	√	_	√	_	$\sqrt{}$	_	SOT23-6/8-QFN
MAX6472	√	_	√	_	_	√	SOT23-6/8-QFN
MAX6473	_	$\checkmark$	√	_	√	_	SOT23-6/8-QFN
MAX6474	_	√	√	_	_	√	SOT23-6/8-QFN
MAX6475	_	√	_	√	√	_	SOT23-6/8-QFN
MAX6476	_	√	_	√	_	√	3×3 UCSP
MAX6477	√	√	_	_	√	_	3×3 UCSP
MAX6478	√	√	_	_	_	√	3×3 UCSP
MAX6479	√	_	√	_	√	_	3×3 UCSP
MAX6480	√	_	√	_	_	√	3×3 UCSP
MAX6481		√	√		√		3×3 UCSP
MAX6482	_	√	√	_	_	√	3×3 UCSP
MAX6483		√		√	√		3×3 UCSP
MAX6484	_	√	_	√	_	√	3×3 UCSP
		1	l				

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#### Package Information

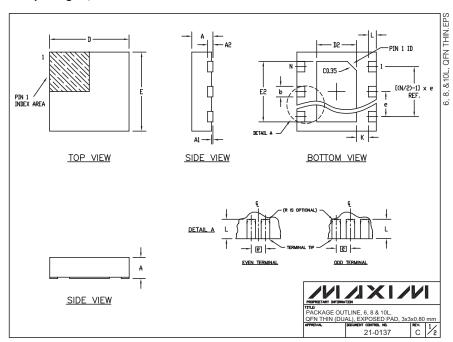
(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)





#### Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



SYMBOL A D E A1	MIN. 0.70 2.90	MAX. 0.80						
D E A1		0.00						
E A1	2.90	0.00						
A1		3.10						
	2.90	3.10						
	0.00	0.05						
L	0.20	0.40						
k		5 MIN						
A2	0.20	REF.						
T633-1	6	1.50-0.10	2.30-0.10	0.95 BSC	MO229 / WEEA	0.40-0.05	1.90 REF	
	-							
T833-1	_	1.50-0.10		0.65 BSC	MO229 / WEEC	0.30-0.05	1.95 REF	
T1033-1	10	1.50-0.10	2.30-0.10	0.50 BSC	MO229 / WEED-3	0.25-0.05	2.00 REF	
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